AMD Sempron[™] Processor Product Data Sheet



Compatible with Existing 32-Bit Code Base

- Including support for SSE, SSE2, SSE3*, MMXTM,
 3DNow!TM technology and legacy x86 instructions
 *SSE3 supported by Rev. E and later processors
- Runs existing operating systems and drivers
- Local APIC on-chip

AMD64 Technology

(Supported by Rev. E3 and later processors)

- AMD64 technology instruction set extensions
- 64-bit integer registers, 48-bit virtual addresses, 40-bit physical addresses
- Eight additional 64-bit integer registers (16 total)
- Eight additional 128-bit SSE registers (16 total)

64-Kbyte 2-Way Associative ECC-Protected L1 Data Cache

- Two 64-bit operations per cycle, 3-cycle latency
- 64-Kbyte 2-Way Associative Parity-Protected L1 Instruction Cache

128-Kbyte 16-Way Associative ECC-Protected L2 Cache

 Exclusive cache architecture—storage in addition to L1 caches

Machine Check Architecture

 Includes hardware scrubbing of major ECC-protected arrays

Power Management

- Multiple low-power states
- System Management Mode (SMM)
- ACPI-compliant, including support for processor performance states

HyperTransport[™] Technology to I/O Devices

 One 16-bit link supporting speeds up to 800 MHz (1600 MT/s) or 3.2 Gigabytes/s in each direction

754-Pin Package Specific Features

 Refer to the AMD Functional Data Sheet, 754-Pin Package, order# 31410, for functional, electrical, and mechanical details of 754-pin package processors.

Packaging

- 754-pin lidded micro PGA
- 1.27-mm pin pitch
- 29x29-row pin array
- 40mm x 40mm organic substrate
- Organic C4 die attach

Integrated Memory Controller

- Low-latency, high-bandwidth
- 72-bit DDR SDRAM at 100, 133, 166, and 200 MHz
- Supports up to three unbuffered DIMMs
- ECC checking with double-bit detect and single-bit correct

Electrical Interfaces

- HyperTransportTM technology: LVDS-like differential, unidirectional
- DDR SDRAM: SSTL_2 per JEDEC specification
- Clock, reset, and test signals also use DDR SDRAM-like electrical specifications